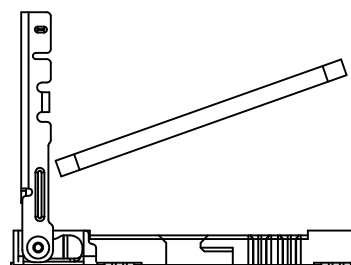
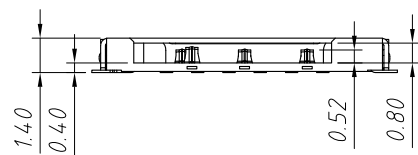


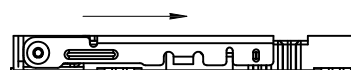
Material:
 Insulator: High Temperature Thermoplastic, UL 94 V-0.
 Contact: C5210, Plated 50u" Ni
 Overall Contact All Au 1U.
 Shell: SUS. All Ni 30U/MIN.

Electrical:
 Current Rating: 0.5A
 Voltage Rating: 5V AC/DC
 Ambient Temperature Range: -40oC ~ +85oC
 Storage Temperature Range: -40oC ~ +85oC
 Ambient Humidity Range: 95% R.H. Max.
 Contact Resistance: 80mΩ Max.
 Insulation Resistance: 100MΩ Min./100V DC
 Mating Cycles: 10000 Insertions.
 Reflow peak temp: 260oC ±5oC, 3~5 s

PCB LAYOUT
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



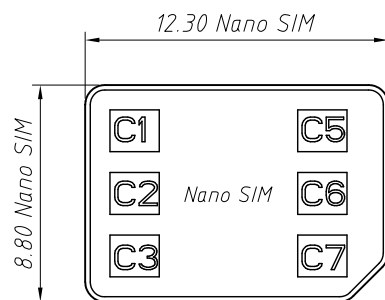
STEP 1 INSERT Micro-SIM CARD




STEP 2 PUSH THE SHELL



STEP 3 FINISH



SIM Card	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I / O

GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION		Description:
X	±0.15	X	±5°	UNITS	mm	
.X	±0.03	.X	±3°	SHEET SIZE	A4	
.XX	±0.05	.XX	±2°		KLS P/N:	
Draw by:	Jenny	Date:	2018-03-10	 NingBo KLS ELECTRONIC CO.,L TD.		
Check by:		Date:	2018-03-10			
SCALE		SHEET	1 OF 1			